General-Chairs

Achim Rettberg
Carl v. Ossietzky University
Oldenburg Germany

Mauro Cesar Zanella
ZF Friedrichshafen
Germany

Co-chair

Franz Ramming
University of Paderborn
Germany

Local-chair

Michael Keckeisen
ZF Friedrichshafen
Germany

Technical-chair

Michael Amann
ZF Friedrichshafen
Germany

Program Comitee

Samar Abdi
University of California
at Irvine, USA

Christian Allmann
Audi Electronics Venture
Germany

Michael Amann
ZF Friedrichshafen
Germany

Richard Anthony
The University of Greenwich
England

Juergen Becker
University Karlsruhe
Germany

Christophe Bobda
University Kaiserslautern
Germany

Florian Dittmann
TWT, Germany

Rainer Doemer
University of California
at Irvine, USA

Cecilia Ekelin
Volvo Technology
Corporation, Sweden

Rolf Ernst
Technical University
Braunschweig, Germany

Masahiro Fujita
University of Tokyo
Japan

Andreas Gerstlauer
University of California
at Irvine, USA

Marcelo Götz
UFRGS, Brazil

Joerg Henkel
University Karlsruhe
Germany

Uwe Honekamp
Vector Informatik
Germany

Marcel Jackowski
USP, Brazil

Michael Keckeisen
ZF Friedrichshafen
Germany

Kane Kim
University of California
at Irvine, USA

Bernd Kleinjohann
C-LAB, Germany

Hermann Kopetz
Technical University Vienna
Austria

Horst Krimmel
ZF Friedrichshafen
Germany

Jean-Claude Laprie
LAAS, France

Thomas Lehmann
Haw, Germany

Armin Lichtblau
Mentor Graphics
Germany

Patrick Lysaght
Xilinx Research Labs
USA

Roger May
Altera, England

Wolfgang Nebel
Carl v. Ossietzky University
Oldenburg Germany

Mike Olivarez
Freescale Semiconductor
Austin, TX

Frank Oppenheimer
OFFIS
Germany

Carlos Pereira
UFRGS
Brazil

Franz Rammig
University Paderborn
Germany

Achim Rettberg
Carl v. Ossietzky University
Oldenburg Germany

Carsten Rust
Sagem Orga
Germany

Stefan Schimpf
ETAS, Germany

Juergen Schimer
Robert Bosch GmbH
Germany

Gunar Schirmer
University of California
at Irvine, USA

Aviral Shrivastava
Arizona State University
USA

Joachim Stroop
dSPACE, Germany

Hiroyuki Tomiyama
Nagoya University
Japan

Ansgar Traechtler
University Paderborn
Germany

Flavio R. Wagner
UFRGS, Brazil

Wayne Wolf
Georgia Institute
of Technologie, USA

Mauro Zanella
ZF Friedrichshafen
Germany

Jianwen Zhu
University of Toronto
Canada

Schloss Montfort
Langenargen

IESS INTERNATIONAL EMBEDDED SYSTEMS SYMPOSIUM '09

call for papers
Sep 14 - 16, 2009
Langenargen
www.iess.org

Antriebs- und Fahrwerktechnik

Conference theme

Over recent years, embedded systems have gained an enormous amount of processing power and functionality.

Many of the formerly external components can now be integrated into a single System-on-Chip. This tendency has resulted in a dramatic reduction of the size and cost of embedded systems. As an unique technology, the design of embedded systems is an essential element of many innovations.

Embedded systems meet their performance goals, including real-time constraints, through a combination of special-purpose hardware and software components tailored to the system requirements. Both the development of new features and the reuse of existing intellectual property components are essential to keeping up with ever demanding customer requirements. Furthermore, design complexities are steadily growing with an increasing number of components that have to cooperate properly. Embedded system designers have to cope with multiple goals and constraints simultaneously, including timing, power, reliability, dependability, maintenance, packaging and, last but not least, price. The significance of these constraints varies depending on the application area a system is targeted for. Typical embedded applications include multi-media, automotive, medical, and communication devices.

The goals of the International Embedded Systems Symposium are to present, exchange and discuss the state of the art, novel ideas, actual research results, and future tendencies in the field of embedded systems. Contributors and participants from both industry and academy are encouraged to take active part in this symposium.

Location

"Schloss Montfort"
Langenargen, Germany

Conference Date

Sep 14 - 16, 2009

Paper submission due

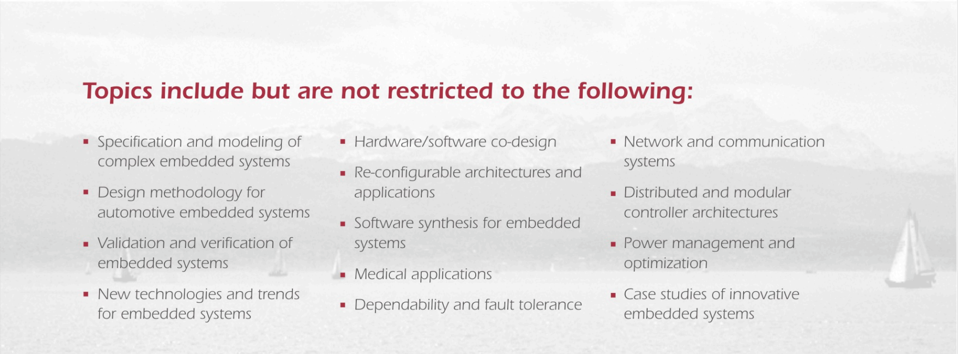
April 5, 2009

Tutorial submission due

April 1, 2009

Support

IFIP - http://www.ifip.org/



Topics include but are not restricted to the following:

- Specification and modeling of complex embedded systems
- Design methodology for automotive embedded systems
- Validation and verification of embedded systems
- New technologies and trends for embedded systems
- Hardware/software co-design
- Re-configurable architectures and applications
- Software synthesis for embedded systems
- Medical applications
- Dependability and fault tolerance
- Network and communication systems
- Distributed and modular controller architectures
- Power management and optimization
- Case studies of innovative embedded systems

Submission

A submission should consist of:

A cover page including: most appropriate topic, title of the paper, names and affiliations of authors, contact author's name, address, phone number, fax number, and email address.

The paper (up to 10 pages in 11 point or larger) or an abstract (3 - 5 pages), which should provide a summary of the main results and their details to allow the program committee to assess their merits and significance, including references and comparisons.

The contribution must be unpublished and not submitted for publication elsewhere, including journals and the proceedings of other symposia or workshops. One author of each accepted paper should present it at the conference.

The Proceedings will be published by Springer, the official publisher of IFIP. Full details on how to format your paper can be found at at the IESS 2009 web site www.iess.org or the web site of the conference publisher, Springer: www.wkap.com/ifip/styles/

You can submit Postscript, PDF, or MS Word files to: IESS@iess.org

IESS '09
www.iess.org